

## Title (en)

PRESS-IN CONTACT FOR CONNECTING AN ELECTRONIC COMPONENT TO A PRINTED CIRCUIT BOARD AND PRESS-IN TOOL FOR PRODUCING A PRESS-IN CONTACT

## Title (de)

EINPRESSKONTAKT ZUR VERBINDUNG EINES ELEKTRONISCHEN BAUELEMENTES MIT EINER LEITERPLATTE SOWIE EINPRESSWERKZEUG UND VERFAHREN ZUR HERSTELLUNG EINES EINPRESSKONTAKTES

## Title (fr)

CONTACT À INSÉRER POUR RELIER UN COMPOSANT ÉLECTRONIQUE À UNE CARTE DE CIRCUITS IMPRIMÉS AINSI QU'OUTIL D'INSERTION ET PROCÉDÉ POUR FABRIQUER UN CONTACT À INSÉRER

## Publication

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## Application

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## Abstract (en)

[origin: WO2010142289A2] The invention relates to a press-in contact and to a press-in tool for connecting an electronic component to a printed circuit board, the press-in contact of the electronic component being pressed into a contact opening of the printed circuit board by means of the press-in tool. The invention also relates to a method for producing a press-in contact. The press-in contact according to the invention comprises at least one guide region which can be received in a guide contour of the press-in tool in a position-fixing manner. The maximum length of the guide region is a multiple of the maximum width or is substantially equal to or only slightly shorter than the maximum width and/or the guide region is highly rigid in the press-in direction (z direction) and flexible in the other directions (x/y directions). The method according to the invention is characterized in that contiguous (interlinked) contours of the press-in contacts, which contours are produced as a tape, are supplied to a division station and are subdivided into individual press-in contacts in predetermined points of separation.

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